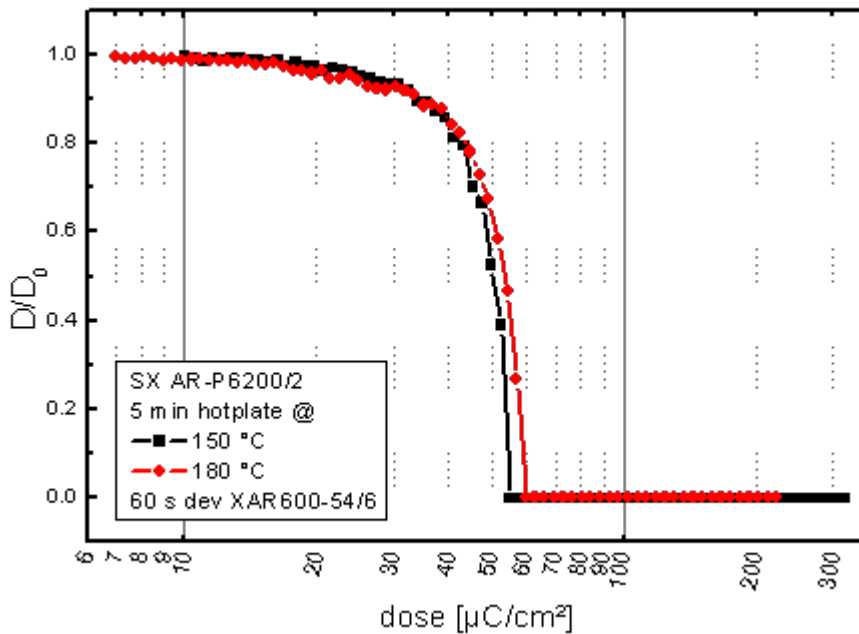


E-Mail correspondence with Christian Kaiser, AllResist, May 2014

Dear Tine,

thank you for your message. Well, you are right, the recommended soft bake time seems to have changed a bit. Here we just want to give an orientation. I think there isn't any significant difference (resolution, sensitivity) to be expected. For thicker layers (>200nm) increasing the soft bake time to about 2 -3 minutes eventually might be advantageous. A soft bake could be proceeded at 180°C as well. Following a direct comparison for different soft bake conditions (30kV, experiments maintained by our partners at MLU Halle, Germany, in 2013):



There isn't any significant difference. So in summary I think the soft bake is not a very critical step in the process.

Please let me know if you have any further questions.

With best regards

Christian

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Von: Tine Greibe [<mailto:tigre@danchip.dtu.dk>]
Gesendet: Freitag, 2. Mai 2014 15:18
An: Christian Kaiser
Betreff: RE: diluter AR 600-02

Dear Christian,

I can see you have changed the procedure and are now recommending a 1 min softbake at 150 degrees Celsius as opposed to last year, where you recommended 3-5 minutes at same temperature? Do you get better resolution with shorter softbake?

BR and thanks!

Tine